

ABSTRACT OF THE DISCLOSURE

A mounting structure of a semiconductor package can improve resistance against thermal and mechanical external
5 force. The mounting structure of a semiconductor package establishes electrical connection of a pad on a printing circuit board to a connection wiring by soldering the semiconductor package. The pad may be integrally formed with a via. The soldering may be performed by penetrating a part of solder within
10 the via so that the connection wiring is connected to the pad through the via at a layer different from a layer of the pad.